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(71)Applicant : KANEGAFUCHI CHEM IND CO LTD

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(72)Inventor : FURUYA HIROYUKI
KIKUCHI TAKESHI
TSUJI HIROYUKI

(54) POLYIMIDE-BASED ADHESIVE SOLUTION, AND FILMY ADHESIVE MEMBER AND FILMY LAMINATING MEMBER PREPARED THEREFROM

(57)Abstract:

PROBLEM TO BE SOLVED: To prepare a polyimide-based adhesive solution, which can control the residual solvent that is responsible for foaming, and the like, and has sufficient heat resistance and adhesive properties, and a filmy laminating member prepared therefrom.

SOLUTION: The polyimide-based adhesive solution is obtained by dissolving a thermoplastic polyimide resin prepared from a specific acid dianhydride, an epoxy resin and a curing agent in an organic solvent comprising a ketonic solvent and/or a cyclic ether solvent. The filmy adhesive member and the filmy laminating member prepared from the solution have sufficient heat resistance and adhesive properties and have no defects of foaming, and the like.

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